

Product Texts

This LCP is designed for low dielectric constant (Dk), excellent flow characteristics & mechanical strength and high temperature resistance. For use in injection molded electronics applications for thin walls.

Flammability @0.4mm nom. V-0
thickn.

Processing/Physical Characteristics	Value	Unit	Test Standard
ISO Data			
^[C] Molding shrinkage, parallel	0.1	%	ISO 294-4, 2577
^[C] Molding shrinkage, normal	0.5	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	Value	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	7400	MPa	ISO 527
^[C] Stress at break	100	MPa	ISO 527
^[C] Strain at break	1.9	%	ISO 527
^[C] Charpy impact strength, +23°C	6.3	kJ/m ²	ISO 179/1eU

[C]: CAMPUS

Thermal properties	Value	Unit	Test Standard
ISO Data			
^[C] Melting temperature, 10°C/min	350	°C	ISO 11357-1/-3
^[C] Temp. of deflection under load, 1.80 MPa	290	°C	ISO 75-1/-2
^[C] Coeff. of linear therm. expansion, parallel	15	E-6/K	ISO 11359-1/-2
^[C] Coeff. of linear therm. expansion, normal	50	E-6/K	ISO 11359-1/-2

[C]: CAMPUS

Electrical properties	Value	Unit	Test Standard
ISO Data			
^[C] Relative permittivity, 1MHz	2.7	-	IEC 62631-2-1
^[C] Dissipation factor, 1MHz	70	E-4	IEC 62631-2-1

[C]: CAMPUS